



SPECIFICATION (Reference sheet)

• Supplier : Samsung electro-mechanics • Samsung P/N : CL05B153KA5NNNC

• Product : Multi-layer Ceramic Capacitor • Description : CAP, 15nF, ±10%, 25V, X7R, 0402

A. Samsung Part Number

<u>CL</u> <u>05</u> <u>B</u> <u>153</u> <u>K</u> <u>A</u> <u>5</u> <u>N</u> <u>N</u> <u>N</u> <u>C</u> ① ② ③ ④ ⑤ ⑥ ⑦ ⑧ ⑨ ⑩ ⑪

① Se	eries	Samsung Multi-layer Ceramic Capacitor			
② Si	ize	0402 (inch code)	L: 1.0	± 0.05 mm	W: 0.5 ± 0.05 mm
3 Di	ielectric	X7R	(8)	Inner electrode	Ni
1	apacitance	15 nF	•	Termination	Cu
⑤ Ca	apacitance	$\pm 10\%$		Plating	Sn 100% (Pb Free)
to	lerance		9	Product	Normal
6 Ra	ated Voltage	25 V	10	Special	Reserved for future use
⑦ Th	nickness	0.5 ± 0.05 mm	11)	Packaging	Cardboard Type, 7" reel

B. Samsung Reliability Test and Judgement condition

	Performance	Test condition			
Capacitance	Within specified tolerance	1kltz±10% 1.0±0.2Vrms			
Tan δ (DF)	0.025 max.				
Insulation	10,000Mohm or 500Mohm⋅μF	Rated Voltage 60~120 sec.			
Resistance	Whichever is Smaller				
Appearance	No abnormal exterior appearance	Microscope (×10)			
Withstanding	No dielectric breakdown or	250% of the rated voltage			
Voltage mechanical breakdown					
Temperature	X7R				
Characteristics	(From -55℃ to 125℃, Capacitance change should be within ±15%)				
Adhesive Strength	No peeling shall be occur on the	500g·F, for 10±1 sec.			
of Termination	terminal electrode				
Bending Strength	Capacitance change: within ±12.5%	Bending to the limit (1mm)			
		with 1.0mm/sec.			
Solderability	More than 75% of terminal surface	SnAg3.0Cu0.5 solder			
	is to be soldered newly	245±5℃, 3±0.3sec.			
		(preheating: 80~120℃ for 10~30sec.)			
Resistance to	Capacitance change: within ±7.5%	Solder pot : 270±5℃, 10±1sec.			
Soldering heat	Tan δ, IR : initial spec.				

	Performance	Test condition	
Vibration Test Capacitance change: within ±5		Amplitude : 1.5mm	
	Tan δ, IR : initial spec.	From 10Hz to 55Hz (return : 1min.)	
		2hours × 3 direction (x, y, z)	
Moisture Capacitance change: within ±12.5%		With rated voltage	
Resistance	Tan δ : 0.05 max	40±2℃, 90~95%RH, 500+12/-0hrs	
	IR: 500Mohm or 25Mohm · μF		
	Whichever is Smaller		
High Temperature	Capacitance change: within ±12.5%	With 200% of the rated voltage	
Resistance	Tan δ : 0.05 max	Max. operating temperature	
	IR: 1000Mohm or 50Mohm $\cdot \mu$ F		
	Whichever is Smaller	1000+48/-0hrs	
Temperature	Capacitance change: within ±7.5%	1 cycle condition	
Cycling	Tan δ, IR : initial spec.	Min. operating temperature → 25°C	
		→ Max. operating temperature → 25°C	
		5 cycle test	

C. Recommended Soldering method:

Reflow (Reflow Peak Temperature : 260+0/-5°C, 10sec. Max)



A Product specifications included in the specifications are effective as of March 1, 2013.

Please be advised that they are standard product specifications for reference only.

We may change, modify or discontinue the product specifications without notice at any time.

So, you need to approve the product specifications before placing an order.

Should you have any question regarding the product specifications,

please contact our sales personnel or application engineers.